

Quantifying Allowable AC parameters for DC Rated Ceramic Capacitors

APEC 2015 Charlotte, NC March 15-19, 2015

Jeremy Coe Applications Engineer - Ceramic Capacitor Division TDK Corporation of America Jeremy.Coe@us.tdk.com 972-409-4510

Space constraints of modern AC powered applications have driven the demand for volumetric efficient products.

- noticeable application Trends driving the use of high performing DC rated capacitors
- discuss the Difficulties of traditional data support for these applications
- provide Keys to overcoming the obstacles set forth









3

公TDK

Wireless Power Transition Circuit



Stringent AC Power Levels

- Voltage is in kV range
- Current is in 10's of Amps range

Key Capacitor Requirements

- Stability with Voltage/Temp
- High Ripple (Low ESR)
- Low Loss (Low D.F.)
- Small Area Consumption
- High Reliability

☆TDK



Design of XTR2 (Class is the finition and element here, but can come at a price. Therefore, MLCOVIDPIIERS have been and the sign engineers to verify compliance with end application requirement engineers is an engineer state of the state of th

• Quality Factor is orders of magnitude higher than COG dielectrics

Technology Comparison

Film capacitors are intriguing because of the high values and stability provided



6



- Must define AC Voltage ratings
- Must provide ESR values in lower frequency range for key COG[NPO] dielectric products
- Must define AC Current ratings
- Must offer ancillary data^{*} to validate use, industry perception, or confusion in AC power applications

*Including reliability concerns

MLCC Supplier Requirements

Rating MLCCs for AC Voltage use has created an unfamiliar position for MLCC suppliers as this product's intended purpose has been DC environments.



- Measurement Data not readily available
- Testing requires new equipment

AC Voltage Measurement Challenge

AC VOLTAGE RATING

- 1. Operating voltage across the terminals should be below the rated voltage. When AC and DC are super imposed, V0-P must be below the rated voltage. Reference: figures 1 and 2 below.
 - AC or pulse with overshooting, VP-P must be below the rated voltage. Reference figures 3, 4, and 5 below.
 - When the voltage is started/ stopped to apply to the circuit an irregular voltage may be generated for a transit period because of resonance or switching. Be sure to use the capacitor within rated voltage during these Irregular voltage periods.



Voltage Cautions from TDK's general specification





Obtain an AC voltage rating from a DC rated MLCC by substituting the peak to peak voltage (Vpp) for the capacitor's rated voltage and solve for Vrms.

Therefore, a 630Vdc rated MLCC would have the following correlated AC rating:

$$V_{\rm rms} = \frac{630Vpp}{2\sqrt{2}} = 222V \rm rms^1$$

¹It is worth noting the intention of use is by no means a guarantee for any safety critical AC application where there is potentially a risk of bodily injury.

Maximum allowable rms voltage

☆TDK



Molecular structure of a Class II dielectric material (Barium Titanate BaTiO3)

AC Voltage effect on DC Rated Capacitors



Spontaneous Polarization



Dipole Alignment to Electric Field



AC Influence: Switching of Polarity

AC Voltage effect on DC Rated Capacitors





Crystal Structure (CaZrO₃)

- Does not have domains
- Zr does not shift
- Less heating affect



Bold Black Line: Crystal Grain

Thin Lines: Domain

Arrows: Dipoles

AC Voltage effect on DC Rated Capacitors

ESR is the key parasitic element of all capacitor technologies used for calculating heat generation



- Re: Electrode Resistance
- Cp: Capacitance
- Rh: Hysteresis Derived Resistance, R/f
- ESL: Equivalent Series Inductance

 $ESR = \rho * L/(W * d)$

Part 1: Purely electrical resistance. Due to terminal and inner electrodes (metal components)

- P = resistivity of internal electrode
- L = total length of MLCC
- W = width of internal electrode
- t = thickness of internal electrode
- n = number of internal electrode

ESR = (R_{Sn} + R_{Ni} + R_{Cu} + R_{elec}) + (R_{h}) + (R_{elec} + R_{Cu} + R_{Ni} + R_{Sn}) = D.F. x X_C Part 2: Affected by the dielectric loss of the ferroelectric ceramic material

Equivalent Series Resistance (ESR)

⊗TDK

LOW FREQUENCY ESR DATA



Due to maccucanies in our ently available data, end a surements of BSR in Acqueency ranges below 1 MHz have been a challenge for all MLCC suppliers.

Due to measurement errors, modeled data is being proposed as an alternate solution



Comparison of Actual and Modeled ESR data

Case Size	Temperature Coefficient	Voltage (V)	Cap Value	ESR at desired measurement frequency									
				60Hz	120Hz	20kHz	50kHz	70kHz	90kHz	100kHz	200kHz	300kHz	400kHz
0402	COG	50	1nF	14076.20	3521.91	3.94	3.83	3.82	3.82	3.82	3.81	3.82	3.83
0603	COG	50	1.2nF	11730.97	2935.73	4.09	4.00	3.99	3.99	3.99	3.99	4.00	4.00
0603	COG	50	1.5nF	9384.19	2348.00	2.68	2.61	2.61	2.60	2.60	2.61	2.62	2.63
0603	COG	50	1.8nF	7820.33	1956.84	2.41	2.35	2.34	2.34	2.34	2.35	2.36	2.38
0603	COG	50	2.2nF	6399.48	1602.08	3.00	2.95	2.95	2.95	2.95	2.95	2.96	2.97
0603	COG	50	2.7nF	5214.51	1305.51	2.56	2.52	2.52	2.51	2.51	2.52	2.53	2.55
0603	COG	50	3.3nF	4266.18	1067.91	1.86	1.83	1.82	1.82	1.82	1.83	1.85	1.87
0603	COG	50	3.9nF	3610.47	904.24	2.20	2.17	2.17	2.17	2.17	2.17	2.19	2.20
0603	COG	50	4.7nF	2996.46	750.87	2.36	2.34	2.34	2.34	2.34	2.35	2.36	2.37
0603	COG	50	5.6nF	2515.35	630.66	2.45	2.43	2.43	2.43	2.43	2.43	2.44	2.46
0603	COG	50	6.8nF	2071.03	518.93	1.58	1.56	1.56	1.56	1.56	1.57	1.59	1.61
0603	COG	50	8.2nF	1718.66	431.55	2.53	2.51	2.51	2.51	2.51	2.52	2.53	2.55
1206	COG	630	10nF	1408.80	353.37	1.57	1.56	1.56	1.57	1.57	1.59	1.63	1.68
1210	COG	630	15nF	939.46	235.84	1.31	1.30	1.31	1.31	1.31	1.35	1.42	1.51
1210	COG	630	22nF	640.69	160.95	1.05	1.04	1.05	1.05	1.06	1.11	1.19	1.30
1206	COG	250	22nF	640.61	160.87	0.96	0.96	0.96	0.96	0.97	1.00	1.06	1.14
1210	COG	630	33nF	427.20	107.37	0.77	0.77	0.77	0.78	0.79	0.85	0.96	1.09
1206	COG	100	33nF	427.30	107.47	0.87	0.87	0.87	0.88	0.88	0.92	0.99	1.07
1812	COG	630	47nF	300.45	75.89	1.04	1.05	1.05	1.06	1.07	1.15	1.28	1.43
1210	COG	250	47nF	300.28	75.72	0.87	0.87	0.88	0.88	0.89	0.95	1.04	1.16
2220	COG	630	68nF	141.42	35.87	0.70	0.70	0.71	0.72	0.72	0.81	0.94	1.09
1812	COG	450	68nF	207.38	52.17	0.44	0.45	0.47	0.49	0.50	0.66	0.84	1.01
2220	COG	630	100nF	141.16	35.61	0.44	0.45	0.46	0.47	0.48	0.61	0.76	0.92
1812	C0G	250	100nF	141.16	35.61	0.44	0.45	0.47	0.49	0.50	0.66	0.84	1.01
2220	COG	250	150nF	94.09	23.73	0.28	0.30	0.31	0.34	0.35	0.50	0.65	0.77
1812	COG	50	220nF	64.31	16.34	0.35	0.37	0.39	0.41	0.43	0.60	0.78	0.92

sheet is calculated by equivalent circuit model for Class

- ECM created using ADS simulation _
- Organized in excel to compare simulated and measured data (at higher frequency)



Originally Modeled Data



Equipment:

- Waveform Generator Bipolar Power Supply Oscilloscope Infrared Thermometer Current Probe/Amplifier
- : HP 3312A
- : NF 4025
- : HP infinium 54845A
- : TASCO THI-301
- : Tektronix A6032/AM503B





	TDK Land Pattern						
Chip Size	а	b	С				
C1005	0.40	1.50	0.50				
C1608	1.00	3.00	1.20				
C2012	1.20	4.00	1.65				
C3216	2.20	5.00	2.00				
C3225	2.20	5.00	2.90				
C4532	3.50	7.00	3.70				
C5750	4.50	8.00	5.60				
C7563	5.50	9.10	6.90				

Initial Challenge: limited measurement due to lack of equipment investment

How to Measure Heat Generation



For proper calculation of the AC current rating, one must know several parameters.

Considerations for Delta T

Series	K (°C/W)
CKG57K/N	460
(2220+)	
CKG45K/N	488
(1812+)	
5750	240
(2220)	
4002	540
(1812)	
3225	370
(1210)	
3216	380
(1206)	
2012	470
(0805)	
1608	740
(0603)	
1005	800
(0402)	
0603	800
(0201)	
0402	800
(01005)	

- May not be publicly released
- Can vary product to product, supplier to supplier, material to material
- TDK provides in its SEAT design tool when simulating for ripple current
- 240 °C/W is used to represent the 2220 package

Thermal Resistance (K or R_{th})

⊘TDK



ESR is typically readily available through design tools. However, one may need to obtain ESR curves from the supplier.

Referencing the same 2220/C0G/250V/150nF/5% capacitor and an operating frequency of 100kHz, the ESR was modeled to approximately 0.35mOhm.

$$I_{rms} = \sqrt{\frac{\Delta T}{K \times ESR}}$$
 $I_{rms} = \sqrt{\frac{20^{\circ}C}{240^{\circ}C/W \times 0.000350hm}} = 15.46A_{rms}$

Maximum allowable rms ripple current

TDK Multilayer Ceramic Capacitor (Estimated Failure Rate FIT)												
TDK PN	TC	RV	Test Temp (°C)	Test Voltage (Vdc)	Tast Time (her)	Oty	Component Hrs.	Est. Operating Temp	Est. Operating	Failure	MTBF	15 year Lifetime
IDAIN	1.0.	к. <i>у</i> .	Test Temp (C)	Test voltage (vac)	1 est 1 time (nrs)	\$9.	Tested (Hrs)	(°C)	Voltage (Vdc)	Rate	(years)	Probability
		250	125	300	1000	77	77,000	105	200	882.15	1.29E+02	89%
2220/C0G/250V/150nF/5%	C0G							125	200	3528.62	3.24E+01	63%
								145	200	14114.48	8.09E+00	16%
	C0G	250	125	300	1000	77	77,000	105	200	882.15	1.29E+02	89%
1812/C0G/250V/100nF/5%								125	200	3528.62	3.24E+01	63%
								145	200	14114.48	8.09E+00	16%
1210/C0G/250V/47nF/5%	C0G	250	125	375	1000	77	77,000	105	200	451.66	2.53E+02	94%
								125	200	1806.65	6.32E+01	79%
								145	200	7226.61	1.58E+01	39%
	C0G	250	125	375	1000	77	77,000	105	200	451.66	2.53E+02	94%
1206/C0G/250V/22nF/5%								125	200	1806.65	6.32E+01	79%
								145	200	7226.61	1.58E+01	39%
0805/C0G/250V/10nF/5%	C0G	250	125	375	1000	77	77,000	105	200	451.66	2.53E+02	94%
								125	200	1806.65	6.32E+01	79%
								145	200	7226.61	1.58E+01	39%
Evanating examples to provide the second sec												

As temperature increases by 20 °C, the FIT is also increasing at a rate of 4 x while the MTBF is reducing by 4 x

Calculations of failure rate with 60% confidence level

1. Voltage Acceleration Coefficient (Av)	2. Temperature Acceleration Coefficient (At)	3. Failure Rate ()	4. Failure Rate with acceleration (λο)
$A_{v} = \boxed{\underbrace{V_{o}}^{3}}_{V_{o}}$	$At = 2 \frac{T - To}{10}$	$\lambda = \underbrace{\mathbf{r}}_{\sum t} \mathbf{x} \mathbf{k}$	$\boldsymbol{\lambda}\boldsymbol{o} = \frac{\boldsymbol{\lambda}}{\operatorname{Av} \mathbf{x} \operatorname{At}} (FIT)$
V : Test voltage	T : Testing temperature	r : Number of failure	1 FIT = 1 x 10 ⁻⁹
Vo : Estmated operating voltage	To : Estimated operating temperature	Σt: Total testing time	
		k : Constant which is changed by	f 5. MTBF (Mean Time Between Failure)
	Lifetime Probability	If r = 0, then k is 0.917	MTBF = 1 / FR
Calculated per the JIS C5003 standard	$R(t) = e^{-t/MTBF}$	-	

<u>Disclaimer</u>: Calculations provided are estimates of product life based on details above, actual performance may vary. TDK does not guarantee the life of its MLCCs. The predicted failure rates in failure per billion device-hours (FIT)

RELIABILITY CONCERNS

<mark>⊘TD</mark>K

- Voltage and temperature are the two main contributors to an MLCC's reliability over a specific time period.
- AC conditions have a more adverse effect on a DC rated MLCC than a pure DC voltage.
- By not adhering to the guidelines presented into today's presentation, the potential failure mode is an electrical short caused by thermo-electric induced stress.

Failure Detection

 Through destructive physical analysis (DPA) cross sectioning and inspection under magnification (50 to 200x), this failure mode is detectable by MLCC suppliers.





25



This software is protected by copyright law and international treaties. Copyright(C)2000-2013 TDK Corporation. All rights reserved.

- Increased functionality vs website
- Obtain Ripple Current across an entire frequency range (i.e. 300kHz-10MHz)
- Compare up to 16 products at once (vs 4)
- Added feature of series and or parallel component combination



ESR and Ripple Current graphs for a 1812/C0G/50V/100nF/5% MLCC

Design Resources

http://product.tdk.com/en/technicalsupport/seat/

- DC rated MLCCs can prove to be a reliable solution for modern noncritical AC applications, if used with proper design considerations.
- Knowing a product's maximum AC voltage and current capability are critical to the optimization of this process and this presentation has provided a platform to obtain these values.
- Mitigation of reliability concerns and readily available data will continue to be at the forefront of this movement as the incorporation of volumetric efficient products are considered.
- Suppliers must continue to support data requirements and readily share via their websites and/or design tools

Summary

